

#### **Features**

- ESD Protect for 5 Lines with Uni-directional
- Provide ESD protection for the protected line to IEC 61000-4-2 (ESD) ±18kV (air), ±18kV (contact)
   IEC 61000-4-4 (EFT) 60A (5/50ns)
   Cable Discharge Event (CDE)
- Small SOT563 package saves board space
- Protect five I/O lines or five power lines
- Fast turn-on and Low clamping voltage
- Low operating voltage: 3.3V and below
- Solid-state silicon-avalanche and active circuit triggering technology
- Green part available

## **Applications**

- Audio Interfaces Protection
- Computer Interfaces Protection
- Microprocessors Protection
- Serial and Parallel Ports Protection
- Control Signal Lines Protection
- Power lines on PCB Protection
- Latchup Protection

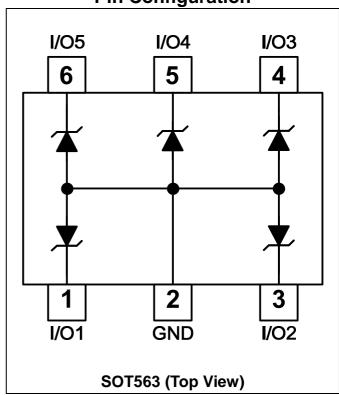
## **Description**

AZ2013-05R is a design which includes five uni-directional ESD rated clamping cells to protect five power lines, or five control lines, or five low speed data lines in an electronic systems. The AZ2013-05R has been specifically designed to protect sensitive components which are connected to power and control lines from over-voltage damage and latch-up caused by Electrostatic Discharging (ESD), Electrical Fast Transients (EFT), and Cable Discharge Event (CDE).

AZ2013-05R is a unique design which includes proprietary clamping cells in a single package. During transient conditions, the proprietary clamping cells prevent over-voltage on the power lines or control/data lines, protecting any downstream components.

AZ2013-05R may be used to meet the ESD immunity requirements of IEC 61000-4-2, Level 4 (±15kV air, ±8kV contact discharge).

# Circuit Diagram / Pin Configuration

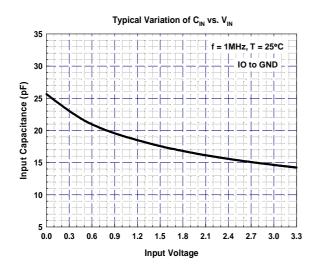


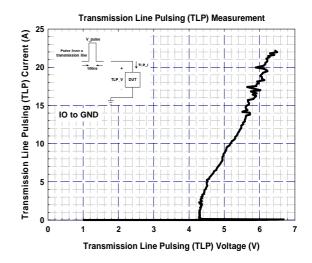
## **SPECIFICATIONS**

ABSOLUTE MAXIMUM RATINGS			
PARAMETER	PARAMETER	RATING	UNITS
Operating Supply Voltage	V <sub>DC</sub>	3.6	V
ESD per IEC 61000-4-2 (Air)	V <sub>ESD</sub>	±18	kV
ESD per IEC 61000-4-2 (Contact)		±18	kV
Lead Soldering Temperature	T <sub>SOL</sub>	260 (10 sec.)	℃
Operating Temperature	T <sub>OP</sub>	-55 to +85	℃
Storage Temperature	T <sub>STO</sub>	-55 to +150	℃

ELECTRICAL CHARACTERISTICS						
PARAMETER	SYMBOL	CONDITIONS	MINI	TYP	MAX	UNITS
Reverse Stand-Off Voltage	V <sub>RWM</sub>	Pin-1, -3, -4, -5, -6 to Pin-2, T= 25 °C			3.3	V
Reverse Leakage Current	I <sub>Leak</sub>	$V_{RWM}$ = 3.3V, T= 25 °C. Pin-1, -3, -4, -5, -6 to Pin-2.			1	μΑ
Reverse DC Breakdown Voltage	V <sub>BV</sub>	$I_{BV}$ = 1mA, T= 25 °C. Pin-1, -3, -4, -5, -6 to Pin-2.	4.5		6.8	V
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 15mA, T= 25 °C. Pin-2 to Pin-1, -3, -4, -5, -6.	0.6		1.0	V
ESD Clamping Voltage	$V_{ESD\_CL}$	IEC 61000-4-2 ±6kV, T= 25 °C, Contact mode, Pin-1, -3, -4, -6 to Pin-2.		6.0		>
Channel Input Capacitance	C <sub>IN</sub>	V <sub>R</sub> = 0V, f = 1MHz, T= 25 °C. Pin-1, -3, -4, -5, -6 to Pin-2.		26	32	pF

## **Typical Characteristics**





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## **Applications Information**

The AZ2013-05R is designed to protect five lines against System ESD/EFT/CDE pulses by clamping them to an acceptable reference.

The usage of the AZ2013-05R is shown in Fig. 1. Protected lines, such as data lines, control lines, or power lines, are connected at pin 1, 3, 4, 5 and 6. The pin2 should be connected directly to a ground plane on the board. In order to minimize parasitic inductance in the board traces, all path lengths connected to the pins of AZ2013-05R should be kept as short as possible.

In order to obtain enough suppression of ESD induced transient, good circuit board is critical. Thus, the following guidelines are recommended:

- Minimize the path length between the protected lines and the AZ2013-05R.
- Place the AZ2013-05R near the input terminals or connectors to restrict transient coupling.
- The ESD current return path to ground should be kept as short as possible.
- Use ground planes whenever possible.
- NEVER route critical signals near board edges and near the lines which the ESD transient easily injects to.

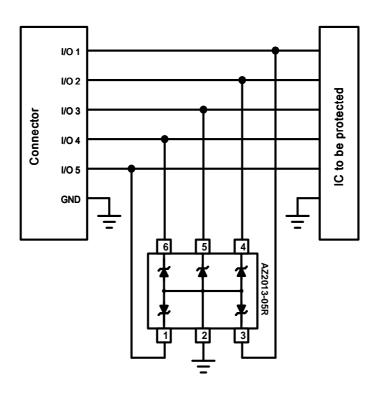
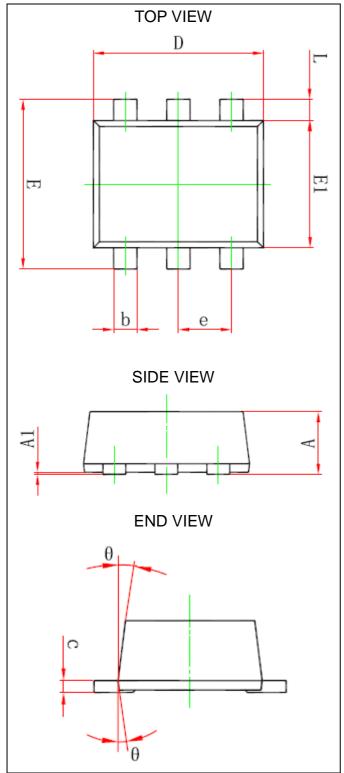


Fig. 1

## **Mechanical Details**

**SOT563** PACKAGE DIAGRAMS

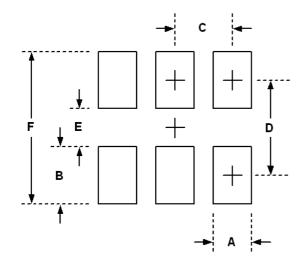


### PACKAGE DIMENSIONS

SYMBOL	Millimeters			
	MIN.	NOMINAL	MAX.	
Α	0.525	-	0.60	
A1	0	-	0.05	
е	0.45	-	0.55	
С	0.09	-	0.16	
D	1.50	-	1.70	
b	0.17	-	0.27	
E1	1.10	-	1.30	
Е	1.50	-	1.70	
L	0.10	-	0.30	
θ	7° REF			



### LAND LAYOUT

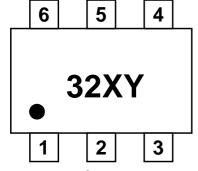


Dimensions		
Index	Millimeter	
Α	0.30	
В	0.50	
С	0.50	
D	1.40	
E	0.90	
F	1.90	

#### Notes:

This LAND LAYOUT is for reference purposes only. Please consult your manufacturing partners to ensure your company's PCB design guidelines are met.

### **MARKING CODE**



32=Device Code X=Date Code Y=Control Code

Part Number	Marking Code
AZ2013-05R (Green Part)	32XY



# **Revision History**

Revision	Modification Description	
Revision 2011/12/01	Preliminary release.	
Revision 2012/05/29	Formal release.	